04-175r2 SAS-1.1 REPORT MANUFACTURER INFORMATION changes

To: T10 Technical Committee From: Rob Elliott, HP (elliott@hp.com) Date: 19 July 2004 Subject: 04-175r2 SAS-1.1 REPORT MANUFACTURER INFORMATION changes

Revision history

Revision 0 (26 May 2004) First revision

Revision 1 (8 July 2004) Incorporated comments from 14 June 2004 conference call - add a bit indicating the new fields are present and it is not all vendor-specific as in SAS-1, and add an 8 byte vendor-specific field. Revision 2 (19 July 2004) Incorporated comments from July SAS protocol WG - use T10 vendor ID string rather than IEEE company ID.

Related documents

sas1r04 - Serial Attached SCSI 1.1 revision 4

Specification for Use of PCI IDs with Windows Operating Systems, Microsoft Corporation, 4 December 2001 (http://www.microsoft.com/whdc/system/bus/PCI/pciidspec.mspx)

<u>Overview</u>

SAS-1 defined four fields in the SMP REPORT MANUFACTURER INFORMATION function:

- a) Vendor ID (8 bytes)
- b) Product ID (16 bytes)
- c) Revision ID (4 bytes)
- d) Vendor-specific (20 bytes)

The first three are in ASCII string format like their corresponding fields in SCSI standard INQUIRY data.

Expanders are usually used on boards where two types of information is equally important:

- a) ASIC information; and
- b) Board information.

To determine what vendor-specific SMP functions can be used, software (either HBA drivers or management software) needs to know the ASIC information, so it's important that such information be reported in standard fields.

For management software to determine what enclosure is being accessed (e.g. to display a picture of it to the user), board information is necessary.

Both kinds of information are needed for bug workarounds. A pure ASIC bug (e.g., some SMP function doesn't work right) can be addressed with knowledge of the ASIC. A board problem (e.g. physical link attached to phy 5 doesn't work) can be addressed with knowledge of the board.

This is the same issue the PCI SIG faced with device vs. subsystem IDs. Microsoft eventually demanded that both the device ID and subsystem device ID fields always be implemented for Windows compliance. They require that:

- a) Vendor ID describes the vendor of the ASIC.
- b) **Device ID** describes the ASIC. It must be unique per the Vendor ID and must change whenever the programming interface is modified.
- c) **Revision ID** describes the revision of the ASIC. It must be incremented for any change (namely software-invisible changes; software-visible changes bump the Device ID and reset this to 0).
- d) Subsystem Vendor ID describes the vendor of the board in which the ASIC is used.
- e) Subsystem ID describes the board in which the ASIC is used. It must change whenever the board is modified (even just changing the value of a resistor), letting software pin-point board-related workarounds without affecting all uses of the ASIC.
- f) There is no **Subsystem Revision ID** field defined; it must be merged into the Subsystem ID.

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This proposal adds a SAS-1.1 mode that changes the response as follows:

- a) the VENDOR IDENTIFICATION, PRODUCT IDENTIFICATION, and PRODUCT REVISION LEVEL fields are defined to carry board information, not ASIC information;
- b) the vendor-specific field are upgraded to a set of standardized fields describing the ASIC -COMPONENT VENDOR IDENTIFICATION, COMPONENT ID, and COMPONENT REVISION LEVEL field. The latter two of these use binary rather than ASCII formats to save space.

Suggested changes

10.4.3.4 REPORT MANUFACTURER INFORMATION function

The REPORT MANUFACTURER INFORMATION function returns vendor and productidentification information about the component (e.g., the expander device) containing the SMP target port and the subsystem (e.g., board or enclosure) containing that component. This SMP function may be implemented by any SMP target port.

Table 1 defines the request format.

Byte\Bit	7	6	5	4	3	2	1	0		
0		SMP FRAME TYPE (40h)								
1		FUNCTION (01h)								
2			Reserved							
3										
4	(MSB)	CRC								
7								(LSB)		

Table 1 — REPORT MANUFACTURER INFORMATION request

The SMP FRAME TYPE field shall be set to 40h.

The FUNCTION field shall be set to 01h.

The CRC field is defined in 10.4.3.1.

Table 2 defines the response format.

Table 2 — REPORT MANUFACTURER INFORMATION response (part 1 of 2)

Byte\Bit	7	6	5	4	3	2	1	0
0	SMP FRAME TYPE (41h)							
1	FUNCTION (01h)							
2	FUNCTION RESULT							
3	Reserved							
4	Ignored							
7								
8	Reserved SAS-1.1 FORMAT							

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Table 2 — REPORT MANUFACTURER INFORMATION response (part 2 of 2)	
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Byte\Bit	7	6	5	4	3	2	1	0	
9		Ignored							
10									
11			Reserved						
12	(MSB)		VENDOR IDENTIFICATION -						
19									
20	(MSB)								
35			PRODUCT IDENTIFICATION -						
36	(MSB)		PRODUCT REVISION LEVEL						
39									
<u>40</u>	<u>(MSB)</u>								
<u>47</u>			COMPONENT VENDOR IDENTIFICATION					<u>(LSB)</u>	
<u>48</u>	<u>(MSB)</u>		COMPONENT ID						
<u>49</u>									
<u>50</u>		COMPONENT REVISION ID							
<u>51</u>			Reserved						
40- <u>52</u>			Vendor specific						
<u>59</u>									
60	(MSB)								
63			CRC					(LSB)	

The SMP FRAME TYPE field shall be set to 41h.

The FUNCTION field shall be set to 01h.

The FUNCTION RESULT field is defined in 10.4.3.2.

A sas-1.1 FORMAT bit set to one indicates that bytes 40 through 59 are as defined in this standard. A sas-1.1 FORMAT field set to zero indicates that bytes 40 through 59 are vendor-specific as defined in the original version of this standard.

The VENDOR IDENTIFICATION field contains eight bytes of ASCII data identifying the vendor of the product. The data shall be left aligned within the field. The vendor identification string shall be one assigned by INCITS foruse in the Standard INQUIRY data VENDOR IDENTIFICATION field. A list of assigned vendor identification stringsis in SPC-3 and on the T10 web site (http://www.t10.org).

The PRODUCT IDENTIFICATION field contains sixteen bytes of ASCII data as defined by the vendor. The datashall be left aligned within the field.

The PRODUCT REVISION LEVEL field contains four bytes of ASCII data as defined by the vendor. The data shallbe left aligned within the field.

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The VENDOR IDENTIFICATION field contains eight bytes of ASCII data identifying the vendor of the subsystem (e.g., the board or enclosure) containing the component. The data shall be left-aligned within the field. The vendor identification string shall be one assigned by INCITS for use in the standard INQUIRY data VENDOR IDENTIFICATION field. A list of assigned vendor identification strings is in SPC-3 and on the T10 web site (http://www.t10.org).

The PRODUCT IDENTIFICATION field contains sixteen bytes of ASCII data identifying the type of the subsystem (e.g., the board or enclosure model number) containing the component, as defined by the vendor of the subsystem. The data shall be left-aligned within the field. The PRODUCT IDENTIFICATION field should be changed whenever the subsystem design changes in a way noticeable to a user (e.g., a different stock-keeping unit (SKU)).

The PRODUCT REVISION LEVEL field contains four bytes of ASCII data identifying the revision level of the subsystem (e.g., the board or enclosure) containing the component, as defined by the vendor of the subsystem. The data shall be left-aligned within the field. The PRODUCT REVISION LEVEL field should be changed whenever the subsystem design changes (e.g., any component change, even including resistor values).

ASCII data fields (e.g., the VENDOR IDENTIFICATION field, the PRODUCT IDENTIFICATION field, and PRODUCT <u>REVISION LEVEL field</u> shall contain only graphic codes (i.e., code values 20h through 7Eh). Left-aligned fields shall place any unused bytes at the end of the field (<u>i.e., at the</u> highest offset) and the unused bytes shall be filled with space characters (<u>i.e.</u>, 20h).

All components on a subsystem should have the same values for their VENDOR IDENTIFICATION fields, PRODUCT IDENTIFICATION fields, and PRODUCT REVISION LEVEL fields.

NOTE 1 Application clients may use the VENDOR IDENTIFICATION field and PRODUCT IDENTIFICATION field to identify the subsystem (e.g., for a user interface). Application clients may use the VENDOR IDENTIFICATION field, PRODUCT IDENTIFICATION field, PRODUCT REVISION LEVEL field to perform workarounds for problems in a specific revision of a subsystem.

The COMPONENT VENDOR IDENTIFICATION field contains eight bytes of ASCII data identifying the vendor of the component (e.g., the expander device) containing the SMP target port. The data shall be left-aligned within the field. The component vendor identification string shall be one assigned by INCITS for use in the standard INQUIRY data VENDOR IDENTIFICATION field. A list of assigned vendor identification strings is in SPC-3 and on the T10 web site (http://www.t10.org).

The COMPONENT ID field contains a 16-bit identifier identifying the type of the component (e.g., the expander device model number) containing the SMP target port, as defined by the vendor of the component. The COMPONENT ID field should be changed whenever the component's programming interface (e.g., the SMP target port definition) changes.

The COMPONENT REVISION LEVEL field contains an 8-bit identifier identifying the revision level of the component (e.g., the expander device) containing the SMP target port, as defined by the vendor of the component. The COMPONENT REVISION LEVEL field should be changed whenever the component changes but its programming interface does not change.

NOTE 2 Application clients may use the COMPONENT VENDOR IDENTIFICATION field and the COMPONENT ID field to interpret vendor-specific information (e.g., vendor-specific SMP functions) correctly for that component. Application clients may use the COMPONENT VENDOR IDENTIFICATION field, the COMPONENT ID field, and the COMPONENT REVISION LEVEL field to perform workarounds for problems in a specific revision of a component.

The vendor-specifc bytes are defined by the vendor of the subsystem (e.g., the board or enclosure) containing the component.

The CRC field is defined in 10.4.3.2.